# **MC100EPT26**

# 1:2 Fanout Differential LVPECL to LVTTL Translator

The MC100EPT26 is a 1:2 Fanout Differential LVPECL to LVTTL translator. Because LVPECL (Positive ECL) levels are used only +3.3V and ground are required. The small outline 8–lead SOIC package and the 1:2 fanout design of the EPT26 makes it ideal for applications which require the low skew duplication of a signal in a tightly packed PC board.

The VBB output allows the EPT26 to be used in a single–ended input mode. In this mode the VBB output is tied to the  $\overline{D0}$  input for a non–inverting buffer or the D0 input for an inverting buffer. If used, the VBB pin should be bypassed to ground via a 0.01µF capacitator.

- 1.4ns Typical Propagation Delay
- 275MHz Fmax (Clock bit stream, not pseudo-random)
- Differential LVPECL inputs
- Small Outline SOIC Package
- 24mA TTL outputs
- Flowthrough Pinouts
- ESD Protection: >2KV HBM, >100V MM
- Internal Input Resistors: Pulldown on D, Pulldown and Pullup on  $\overline{D}$
- Q Outputs will default LOW with inputs open or at  $V_{EE}$
- VBB Output
- New Differential Input Common Mode Range
- Moisture Sensitivity Level 1, Indefinite Time Out of Drypack. For Additional Information, See Application Note AND8003/D
- Flammability Rating: UL–94 code V–0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 117 devices

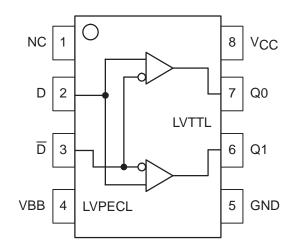
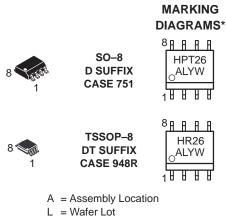


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram



# **ON Semiconductor**

http://onsemi.com





W = Work Week

\*For additional information, see Application Note AND8002/D

PIN DESCRIPTION						
PIN	FUNCTION					
Q0, Q1	LVTTL Outputs					
D, D	Differential LVPECL Input Pair					
VCC	Positive Supply					
V <sub>BB</sub>	Reference Voltage					
GND	Ground					

### **ORDERING INFORMATION**

Device	Package	Shipping			
MC100EPT26D	SO–8	98 Units / Rail			
MC100EPT26DR2	SO–8	2500 / Reel			
MC100EPT26DT	TSSOP-8	98 Units / Rail			
MC100EPT26DTR2	TSSOP-8	2500 / Reel			

## **MAXIMUM RATINGS\***

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	Power Supply (GND = 0V)		0 to 3.8	VDC
VI	Input Voltage (GND = 0V, VI not more positive th	nan V <sub>CC</sub> )	0 to 3.8	VDC
l <sub>out</sub>	Output Current	50 100	mA	
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source Current†	± 0.5	mA	
T <sub>A</sub>	Operating Temperature Range	-40 to +85	°C	
T <sub>stg</sub>	Storage Temperature		-65 to +150	°C
θJA	Thermal Resistance (Junction-to-Ambient)	Still Air 500lfpm	190 130	°C/W
θJC	Thermal Resistance (Junction-to-Case)	41 to 44 $\pm5\%$	°C/W	
T <sub>sol</sub>	Solder Temperature (<2 to 3 Seconds: 245°C de	265	۵°	

\* Maximum Ratings are those values beyond which damage to the device may occur.

† Use for inputs of same package only.

# DC CHARACTERISTICS (V\_{CC} = $3.3V \pm 0.3V$ ; GND = 0V; T<sub>A</sub> = $-40^{\circ}$ C to $85^{\circ}$ C)

Symbol	Characteristic	Min	Тур	Max	Unit
ІССН	Power Supply Current (Outputs set to HIGH)	10	20	18	mA
ICCL	Power Supply Current (Outputs set to LOW)	15	28	35	mA
VIH	Input HIGH Voltage (V <sub>CC</sub> = 3.3) (Note 1.)	2135		2420	mV
VIL	Input LOW Voltage (V <sub>CC</sub> = 3.3) (Note 1.)	1490		1825	mV
IIН	Input HIGH Current			150	μΑ
ΙIL	Input LOW Current D	-150		0.5	μA
VOH	Output HIGH Voltage (I <sub>OH</sub> = -3.0mA) (Note 2.)	2.4			V
VOL	Output LOW Voltage (I <sub>OL</sub> = 24mA) (Note 2.)			0.5	V
los	Output Short Circuit Current	-50		-150	mA
VIHCMR	Input HIGH Voltage Common Mode Range (Note 3.)	2.0		3.3	V
V <sub>BB</sub>	Output Voltage Reference		2.0		V

NOTE: 100EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

1. All values vary 1:1 with V<sub>CC</sub>. 2. All loading with 500 ohms to GND, CL = 20pF. 3. V<sub>IHCMR</sub> min varies 1:1 with GND, max varies 1:1 with V<sub>CC</sub>.

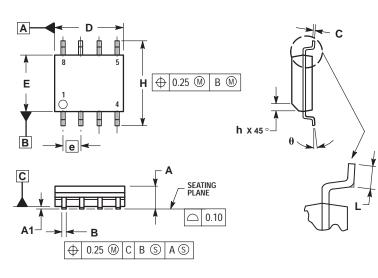
AC CHARACTERISTICS (V<sub>CC</sub> =  $3.3V \pm 0.3V$ ; GND = 0V)

			-40°C		25°C			85°C				
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency (Note 4.)		275	350		275	350		275	350		MHz
<sup>t</sup> PLH, <sup>t</sup> PHL	Propagation Delay to Output Differential (Note 5.)		1.2 1.2	1.5 1.5	1.8 1.8	1.2 1.2	1.5 1.5	1.8 1.8	1.3 1.2	1.7 1.5	2.2 1.8	ns
<sup>t</sup> SK+ + <sup>t</sup> SK <sup>t</sup> SKPP	Output-to-Output Skew++ Output-to-Output Skew Part-to-Part Skew (Note 6.)			60 25 500			60 25 500			60 25 500		ps
<sup>t</sup> JITTER	Cycle-to-Cycle Jitter			TBD			TBD			TBD		ps
VPP	Input Voltage Swing (Diff.)		150	800	1200	150	800	1200	150	800	1200	mV
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Times (0.8V – 2.0V)	Q,	330	600	900	330	600	900	330	650	900	ps

4.  $F_{max}$  guaranteed for functionality only.  $V_{OL}$  and  $V_{OH}$  levels are guaranteed at DC only. 5. Reference ( $V_{CC} = 3.3V \pm 5\%$ , GND = 0V) 6. Skews are measured between outputs under identical transitions.

# PACKAGE DIMENSIONS

SO-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-06 **ISSUE T** 



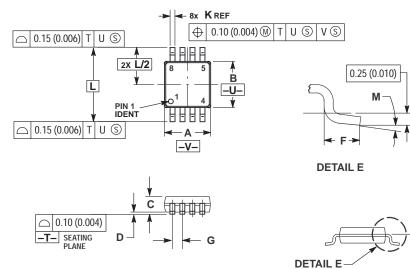
NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. DIMENSIONS ARE IN MILLIMETER. 3. DIMENSION D AND E DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE. 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

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	MILLIMETERS								
DIM	MIN	MAX							
Α	1.35	1.75							
A1	0.10	0.25							
В	0.35	0.49							
С	0.19	0.25							
D	4.80	5.00							
E	3.80	4.00							
e	1.27	BSC							
Н	5.80	6.20							
h	0.25	0.50							
L	0.40	1.25							
θ	0 °	7°							

## **MC100EPT26**

### PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 ISSUE A



 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-MILLIMETERS INCHES DIM MIN MAX MIN MAX 0.114 0.122 3.10 А 2.90 3.10 0.114 0.122 В 2.90 С 0.80 1.10 0.031 0.043 0.15 D 0.05 0.002 0.006 0.40 0.70 0.016 0.028 F G 0.65 BSC 0.026 BSC 0.25 0.40 0.010 0.016 К 4.90 BSC 0.193 BSC L Μ 0° 0°

DIMENSIONING AND TOLERANCING PER ANSI

CONTROLLING DIMENSION: MILLIMETER

DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED

INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT

EXCEED 0.25 (0.010) PER SIDE. 5. TERMINAL NUMBERS ARE SHOWN FOR

0.15 (0.006) PER SIDE. DIMENSION B DOES NOT INCLUDE

NOTES:

2.

3

5.

-w-

Y14.5M, 1982.

REFERENCE ONLY.

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